

Title (en)

RESILIENT PROBES FOR ELECTRICAL TESTING

Title (de)

NACHGIEBIGE SONDEN ZUR ELEKTRISCHEN PRÜFUNG

Title (fr)

SONDES ELASTIQUES CONÇUES POUR ESSAIS ELECTRIQUES

Publication

EP 2569646 A4 20140122 (EN)

Application

EP 06739525 A 20060323

Priority

- US 66567605 P 20050328
- US 11688405 A 20050427
- US 2006010779 W 20060323

Abstract (en)

[origin: WO2006104886A2] An apparatus for electrical testing having probes (201) constructed of metal elements (201a) of about equal size bonded together in substantially linear sequence. Further an insulating holder (202) having first and second surfaces and a plurality of metal-filled vias (210) traversing the holder from the first to the second surface; the vias form contact pads on the first and second surfaces. The contact pads (210a) of the first holder surface have a probe attached so that the probe is positioned about normal to the surface. A sheet (203) of resilient insulating material, which has first and second surfaces and a thickness traversed by a plurality of conducting traces (220), has its first sheet surface attached to the second holder surface so that at least one of the traces contacts one of the contact pads, respectively, to provide an electrical path to the second sheet surface. A printed circuit board, suitable for insertion into an electrical test apparatus, is attached to the second sheet surface so that a continuous electrical path is established from the apparatus to each of the probes.

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

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- See references of WO 2006104886A2

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DE FR GB

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